



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Makoto Yoshino, et al.**  
Serial No.: **09/909,013**  
Filed: **07/19/2001**  
For: **Semiconductor Package Insulation Film  
And Manufacturing Method Thereof**

Docket No.: **TIJ-29448**  
Art Unit: **2829**  
Examiner: **Geyer, Scott B.**  
Conf. No.: **8724**

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NOTICE OF APPEAL

Commissioner For Patents  
Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450

 7/8/2003  
Elizabeth Austin Date

Applicant hereby appeals to the Board of Appeals from the decision dated April 8, 2003, of the Primary Examiner finally rejecting Claims 5-10, 12, 14, 15, and 17-19.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicant  
Reg. No. 36,682

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